APPLICABLE STANDARD				
RATING	OPERATING TEMPERATURE RANGE	-35°C TO +85°C(NOTE 1)	STORAGE TEMPERATURE RANGE	-10°C TO +60°C(NOTE 3)
	OPERATING HUMIDITY RANGE	40 % TO 80 % (NOTE 2)	STORAGE HUMIDITY RANGE	40 % TO 70 %(NOTE 3)
	CURRENT	1 A/pin	VOLTAGE	150 V AC (DC)
	APPLICABLE CONNECTOR	DF14-*S-1.25C	APPLICABLE CONTACT	DF14-****SCFA(##)

SPECIFICATIONS

ITEM	TEST METHOD	REQUIREMENTS	QT	AT
CONSTRUCTION				
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING.	X	X
MARKING	CONFIRMED VISUALLY.		X	X
ELECTRIC CHARACTERISTICS				
CONTACT RESISTANCE	20 mV MAX, 1mA (DC OR 1000 Hz)	30 mΩ MAX.	X	–
INSULATION RESISTANCE	100 V DC.	500 MΩ MIN.	X	–
VOLTAGE PROOF	500 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	X	–
MECHANICAL CHARACTERISTICS				
MECHANICAL OPERATION	50 TIMES INSERTIONS AND EXTRACTIONS.	1) CONTACT RESISTANCE: 30 mΩ MAX. 2) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	–
VIBRATION	FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.	1) NO ELECTRICAL DISCONTINUITY OF 1μs. 2) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	–
SHOCK	490 m/s^2 DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			
ENVIRONMENTAL CHARACTERISTICS				
RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55→ 5 TO 35→ +85→ 5 TO 35 °C TIME 30→ 10 TO 15→30→ 10 TO 15 min. UNDER 5 CYCLES.	1) CONTACT RESISTANCE: 30mΩ MAX. 2) INSULATION RESISTANCE: 500 MΩ MIN. 3) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	–
DAMP HEAT (STEADY STATE)	EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.			
RESISTANCE TO SOLDERING HEAT	1) REFLOW SOLDERING ≪REFLOW AREA≫ MAX 250°C WITHIN 10 sec MIN 230°C WITHIN 60 sec ≪PREHEATING AREA≫ 170°C TO 190°C 60 sec TO 120 sec PUT THROUGH IN REFLOW FUMACE TWICE. LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNECTOR TEMPERTURE TO BE AMBIENT FOR SECOND REFLOW. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE 350±5 °C, FOR5±1 sec. NO STRENGTH ON CONTACT.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	X	–
SOLDERABILITY	SOLDERING TEMPERATURE : 245±5°C DURATION OF IMMERSION : SOLDERING, FOR 3sec.	A NEW UNIFORM COATING OF SOLDER SHALL COVER MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	X	–

REMARKS
NOTE1: INCLUDING THE TEMPERATURE RISE BY CURRENT
NOTE2: NO CONDENSING
NOTE3: APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE MOUNTED ON PCB.
AFTER MOUNTED ON PCB, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION.

	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
⚠0					

Unless otherwise specified, refer to IEC 60512.

APPROVED	HS.OKAWA	20200316
CHECKED	TS.KUMAZAWA	20200316
DESIGNED	HK.HAYASHI	20200316
DRAWN	DS.HIROWATARI	20200311

Note QT: Qualification Test AT: Assurance Test X:Applicable Test

DRAWING NO. ELC-160307-52-00

HRS	SPECIFICATION SHEET	PART NO.	DF14-*P-1.25H(52)	
	HIROSE ELECTRIC CO., LTD.	CODE NO.	CL538	⚠0 1/1

FORM HD0011-2-1